

MATERIAL DECLARATION DATA SHEET

Package: Thoroughbred 27291
 Description: Athlon, OPGA, Brown

Average Weight: 10.1 grams
 Contact: jacquana.diep@amd.com

CONTROLLED MATERIALS

- The product neither contains nor was manufactured with materials listed in Section A of EIA's Material Declaration Template.

RESTRICTED MATERIALS

- The product does not contain listed materials in prohibited applications indicated in Section B of EIA's Material Declaration Template.

MATERIALS OF INTEREST

- The product does contain listed materials of interest as indicated by Section C of EIA's Material Declaration Template. These materials are listed in the following table.

Material of Interest	Reference ¹	Description of Use	wt%	ppm	mg
Antimony	C1a	Pin attachments	< 0.25	< 2,500	< 25
Copper	C1k	Pins and Internal circuitry	< 50	< 500,000	< 5050
Gold	C1l	Internal circuitry & contact plating	< 0.01	< 100	< 1.0
Nickel	C1h	Plating of pins	< 0.3	< 3000	< 30
Pb (Lead)	C1f	Solder bumps & attach	< 5	< 50,000	< 505
Palladium	C1m	Surface mount capacitors / resistors	< 0.1	< 1000	< 10.1
Silver	C1n	Surface mount resistors	< 0.0015	< 15	< 0.15

1. This reference corresponds to the item number of each material of interest as defined in Section C of EIA's Material Declaration Guide (February 2002). See "EIA Materials of Interest" on page 4-10 for a complete listing.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

The following materials are not listed in EIA's Material Declaration Template, but are contained in this package.

Material of Interest	Wt%	ppm	mg
Acrylic	< 0.035	< 350	< 3.5
AL2O3 Ceramic	< 0.20	< 2,000	< 20
Barium Titanate	< 1.5	< 15,000	< 152
Bismuth	< 0.0075	< 75	< 0.76
BT Resin	< 16	< 160,000	< 1616
Epoxy	< 5.0	< 50,0000	< 505
Glass	< 0.0025	< 25	< 0.25
Iron	< 0.80	< 8,000	< 81
Lead-Borate Glass	< 0.01	< 100	< 1.0
Phosphorus	< 0.015	< 150	< 1.5
Polyester	< 0.10	< 1000	< 10.1
Ruthenium Oxide	< 0.0075	< 75	< 0.76
Silicon	< 2.0	< 20,000	< 202
Silicone elastomer	< 1.0	< 10,000	< 101
SiO2 Filler (Fused Silica)	< 1.0	< 10,000	< 101
SiO2 Glass Mesh	< 20	< 200,000	< 2020
Tin	< 0.70	< 7,000	< 70.7
Zinc	< 0.05	< 500	< 5.05

MATERIAL DECLARATION DATA SHEET

Package: Thoroughbred 27648 Average Weight: 10.9 grams
 Description: Athlon, OPGA, Brown Contact: jacquana.diep@amd.com

CONTROLLED MATERIALS

The product neither contains nor was manufactured with materials listed in Section A of EIA's Material Declaration Template.

RESTRICTED MATERIALS

The product does not contain listed materials in prohibited applications indicated in Section B of EIA's Material Declaration Template.

MATERIALS OF INTEREST

The product does contain listed materials of interest as indicated by Section C of EIA's Material Declaration Template. These materials are listed in the following table.

Material of Interest	Reference	Description of Use	Wt%	ppm	mg
Antimony	C1a	Pin attachments	< 0.25	< 2,500	< 27
Copper	C1k	Pins and Internal circuitry	< 56	< 560,000	< 6104
Gold	C1l	Internal circuitry & contact plating	< 0.01	< 100	< 1.1
Nickel	C1h	Plating of pins	< 0.30	< 3,000	< 33
Pb (Lead)	C1f	Solder bumps & attach	< 5	< 50,000	< 545
Palladium	C1m	Surface mount capacitors / resistors	< 0.10	< 1,000	< 10.9
Silver	C1n	Surface mount resistors	< 0.0025	< 25	< 0.27

1. This reference corresponds to the item number of each material of interest as defined in Section C of EIA's Material Declaration Guide (February 2002). See "EIA Materials of Interest" on page 4-10 for a complete listing.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

The following materials are not listed in EIA's Material Declaration Template, but are contained in this package.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

Material of Interest	Wt%	ppm	mg
Acrylic	< 0.03	< 300	< 3.3
AL2O3 Ceramic	< 0.20	< 2,000	< 22
Barium Titanate	< 1.5	< 15,000	< 164
Bismuth	< 0.0075	< 75	< 0.82
BT Resin	< 15	< 150,000	< 1635
Epoxy	< 3	< 30,000	< 327
Glass	< 0.0025	< 25	< 0.27
Iron	< 0.80	< 8,000	< 87
Lead-Borate Glass	< 0.01	< 100	< 1.1
Phosphorus	< 0.015	< 150	< 1.64
Polyester	< 0.10	< 1,000	< 11
Ruthenium Oxide	< 0.0075	< 75	< 0.82
Silicon	< 1.5	< 15,000	< 164
Silicone elastomer	< 1	< 10,000	< 109
SiO2 Filler (Fused Silica)	< 0.60	< 6,000	< 65
SiO2 Glass Mesh	< 18	< 180,000	< 1962
Tin	< 0.70	< 7,000	< 76
Zinc	< 0.05	< 500	< 5.5



MATERIAL DECLARATION DATA SHEET

Package: Barton, 27488 Average Weight: 10.2 grams
 Description: Athlon, OPGA, Brown Contact: jacquana.diep@amd.com

CONTROLLED MATERIALS

The product neither contains nor was manufactured with materials listed in Section A of EIA's Material Declaration Template.

RESTRICTED MATERIALS

The product does not contain listed materials in prohibited applications indicated in Section B of EIA's Material Declaration Template.

MATERIALS OF INTEREST

The product does contain listed materials of interest as indicated by Section C of EIA's Material Declaration Template. These materials are listed in the following table.

Material of Interest	Reference	Description of Use	Wt%	ppm	mg
Antimony	C1a	Pin attachments	< 0.25	< 2,500	< 26
Copper	C1k	Pins and Internal circuitry	< 50	< 500,000	< 5100
Gold	C1l	Internal circuitry & contact plating	< 0.015	< 150	< 1.5
Nickel	C1h	Plating of pins	< 0.31	< 3,100	< 32
Pb (Lead)	C1f	Solder bumps & attach	< 5	< 50,000	< 510
Palladium	C1m	Surface mount capacitors / resistors	< 0.10	< 1,000	< 10.2
Silver	C1n	Surface mount resistors	< 0.0025	< 25	< 0.26

1. This reference corresponds to the item number of each material of interest as defined in Section C of EIA's Material Declaration Guide (February 2002). See "EIA Materials of Interest" on page 4-10 for a complete listing.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

The following materials are not listed in EIA's Material Declaration Template, but are contained in this package.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

Material of Interest	Wt%	ppm	Mg
Acrylic	< 0.035	< 350	< 3.6
AL2O3 Ceramic	< 0.20	< 2,000	< 20
Barium Titanate	< 1.6	< 16,000	< 163
Bismuth	< 0.0075	< 75	< 0.77
BT Resin	< 16	< 160,000	< 1632
Epoxy	< 5	< 50,000	< 510
Glass	< 0.0025	< 25	< 0.26
Iron	< 0.80	< 8,000	< 82
Lead-Borate Glass	< 0.01	< 100	< 1.0
Phosphorus	< 0.0150	< 150	< 1.5
Polyester	< 0.08	< 800	< 8.2
Ruthenium Oxide	< 0.0075	< 75	< 0.77
Silicon	< 2	< 20,000	< 204
Silicone elastomer	< 1.0	< 10,000	< 102
SiO2 Filler (Fused Silica)	< 1.0	< 10,000	< 102
SiO2 Glass Mesh	< 20	< 200,000	< 2040
Tin	< 0.70	< 7,000	< 71
Zinc	< 0.05	< 500	< 5.1



MATERIAL DECLARATION DATA SHEET

Package: Barton, 27493
Description: Athlon, OPGA, Brown

Average Weight: 10.9 grams
Contact: jacquana.diep@amd.com

CONTROLLED MATERIALS

- The product neither contains nor was manufactured with materials listed in Section A of EIA's Material Declaration Template.

RESTRICTED MATERIALS

- The product does not contain listed materials in prohibited applications indicated in Section B of EIA's Material Declaration Template.

MATERIALS OF INTEREST

- The product does contain listed materials of interest as indicated by Section C of EIA's Material Declaration Template. These materials are listed in the following table.

Material of Interest	Reference	Description of Use	Wt%	Ppm	mg
Antimony	C1a	Pin attachments	< 0.22	< 2,200	< 24
Copper	C1k	Pins and Internal circuitry	< 56	< 560,000	< 6104
Gold	C1l	Internal circuitry & contact plating	< 0.01	< 100	< 1.1
Nickel	C1h	Plating of pins	< 0.30	< 3,000	< 33
Pb (Lead)	C1f	Solder bumps & attach	< 4.5	< 45,000	< 491
Palladium	C1m	Surface mount capacitors / resistors	< 0.10	< 1,000	< 11
Silver	C1n	Surface mount resistors	< 0.0025	< 25	< 0.27

1. This reference corresponds to the item number of each material of interest as defined in Section C of EIA's Material Declaration Guide (February 2002). See "EIA Materials of Interest" on page 4-10 for a complete listing.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

The following materials are not listed in EIA's Material Declaration Template, but are contained in this package.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

Material of Interest	Wt%	ppm	Mg
Acrylic	< 0.03	< 300	< 3.3
AL2O3 Ceramic	< 0.20	< 2,000	< 22
Barium Titanate	< 1.5	< 15,000	< 164
Bismuth	< 0.0075	< 75	< 0.82
BT Resin	< 14.5 wt %	< 145,000	< 1581
Epoxy	< 3 wt %	< 30,000	< 327
Glass	< 0.0025	< 25	< 0.27
Iron	< 0.80	< 8,000	< 87
Lead-Borate Glass	< 0.01	< 100	< 1.1
Phosphorus	< 0.015	< 150	< 1.6
Polyester	< 0.10	< 1,000	< 11
Ruthenium Oxide	< 0.0075	< 75	< 0.82
Silicon	< 2	< 20,000	< 218
Silicone elastomer	< 1.0	< 10,000	< 109
SiO2 Filler (Fused Silica)	< 0.60	< 6,000	< 65
SiO2 Glass Mesh	< 18	< 180,000	< 1962
Tin	< 0.70	< 7,000	< 76
Zinc	< 0.05	< 500	< 5.5

MATERIAL DECLARATION DATA SHEET

Package: Thoroughbred, 27291
 Description: Athlon, OPGA, Green

Average Weight: 10.1 grams
 Contact: jacquana.diep@amd.com

CONTROLLED MATERIALS

- The product neither contains nor was manufactured with materials listed in Section A of EIA's Material Declaration Template.

RESTRICTED MATERIALS

- The product does not contain listed materials in prohibited applications indicated in Section B of EIA's Material Declaration Template.

MATERIALS OF INTEREST

- The product does contain listed materials of interest as indicated by Section C of EIA's Material Declaration Template. These materials are listed in the following table.

Material of Interest	Reference	Description of Use	Wt%	ppm	Mg
Antimony	C1a	Pin attachments	< 0.280	< 2,800	< 28
Copper	C1k	Pins and Internal circuitry	< 49	< 490,000	< 4949
Gold	C1l	Internal circuitry & contact plating	< 0.015	< 150	< 1.5
Nickel	C1h	Plating of pins	<0.350	< 3,500	< 35
Pb (Lead)	C1f	Solder bumps & attach	< 5.1	< 51,000	< 515
Palladium	C1m	Surface mount capacitors / resistors	< 0.100	< 1,000	< 10
Silver	C1n	Surface mount resistors	< 0.0025	< 25	< 0.25

1. This reference corresponds to the item number of each material of interest as defined in Section C of EIA's Material Declaration Guide (February 2002). See "EIA Materials of Interest" on page 4-10 for a complete listing.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

The following materials are not listed in EIA's Material Declaration Template, but are contained in this package.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

Material of Interest	Wt%	ppm	Mg
Acrylic	< 0.035	< 350	< 3.5
AL2O3 Ceramic	< 0.200	< 2,000	< 20
Barium Titanate	< 1.5	< 15,000	< 152
Bismuth	< 0.0075	< 75	< 0.76
BT Resin	< 16	< 16,000	< 1616
Epoxy	< 5	< 50,000	< 505
Glass	< 0.0025	< 25	< 0.25
Iron	< 0.800	< 8,000	< 81
Lead-Borate Glass	< 0.010	< 100	< 1.0
Phosphorus	< 0.025	< 250	< 2.5
Polyester	< 0.100	< 1,000	< 10
Ruthenium Oxide	< 0.0075	< 75	< 0.76
Silicon	< 2	< 20,000	< 202
Silicone elastomer	< 1.0	< 10,000	< 101
SiO2 Filler (Fused Silica)	< 1.2	< 12,000	< 121
SiO2 Glass Mesh	< 20	< 200,000	< 2020
Tin	< 0.800	< 8,000	< 81
Zinc	< 0.050	< 500	< 5.1

MATERIAL DECLARATION DATA SHEET

Package: Thoroughbred 27648
 Description: Athlon, OPGA, Green

Average Weight: 11.0 grams
 Contact: jacquana.diep@amd.com

CONTROLLED MATERIALS

- The product neither contains nor was manufactured with materials listed in Section A of EIA's Material Declaration Template.

RESTRICTED MATERIALS

- The product does not contain listed materials in prohibited applications indicated in Section B of EIA's Material Declaration Template.

MATERIALS OF INTEREST

- The product does contain listed materials of interest as indicated by Section C of EIA's Material Declaration Template. These materials are listed in the following table.

Material of Interest	Reference	Description of Use	Wt%	ppm	mg
Antimony	C1a	Pin attachments	< 0.300	< 3,000	< 33
Copper	C1k	Pins and Internal circuitry	< 55	< 550,000	< 6050
Gold	C1l	Internal circuitry & contact plating	< 0.010	< 100	< 1.1
Nickel	C1h	Plating of pins	< 0.300	< 3,000	< 33
Pb (Lead)	C1f	Solder bumps & attach	< 5	< 50,000	< 550
Palladium	C1m	Surface mount capacitors / resistors	< 0.100	< 1,000	< 11
Silver	C1n	Surface mount resistors	< 0.0025	< 25	< 0.28

1. This reference corresponds to the item number of each material of interest as defined in Section C of EIA's Material Declaration Guide (February 2002). See "EIA Materials of Interest" on page 4-10 for a complete listing.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

The following materials are not listed in EIA's Material Declaration Template, but are contained in this package.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

Material of Interest	Wt%	ppm	Mg
Acrylic	< 0.030	< 300	3.3
AL2O3 Ceramic	< 0.200	< 2,000	22
Barium Titanate	< 1.5	< 15,000	165
Bismuth	< 0.0075	< 75	0.83
BT Resin	< 15	< 150,000	1650
Epoxy	< 3	< 30,000	330
Glass	< 0.0025	< 25	0.28
Iron	< 0.800	< 8,000	88
Lead-Borate Glass	< 0.010	< 100	1.1
Phosphorus	< 0.025	< 250	2.8
Polyester	< 0.100	< 1,000	11
Ruthenium Oxide	< 0.0075	< 75	0.83
Silicon	< 1.5	< 15,000	165
Silicone elastomer	< 1.0	< 10,000	110
SiO2 Filler (Fused Silica)	< 0.900	< 9,000	99
SiO2 Glass Mesh	< 18	< 180,000	1980
Tin	< 0.700	< 7,000	77
Zinc	< 0.050	< 500	5.5

MATERIAL DECLARATION DATA SHEET

Package: Barton, 27488 Average Weight: 10.6 grams
 Description: Athlon, OPGA, Green Contact: jacquana.diep@amd.com

CONTROLLED MATERIALS

The product neither contains nor was manufactured with materials listed in Section A of EIA's Material Declaration Template.

RESTRICTED MATERIALS

The product does not contain listed materials in prohibited applications indicated in Section B of EIA's Material Declaration Template.

MATERIALS OF INTEREST

The product does contain listed materials of interest as indicated by Section C of EIA's Material Declaration Template. These materials are listed in the following table.

Material of Interest	Reference	Description of Use	Wt%	ppm	mg
Antimony	C1a	Pin attachments	< 0.260	< 2,600	< 28
Copper	C1k	Pins and Internal circuitry	< 52	< 520,000	< 5512
Gold	C1l	Internal circuitry & contact plating	< 0.015	< 150	< 1.6
Nickel	C1h	Plating of pins	< 0.300	< 3,000	< 32
Pb (Lead)	C1f	Solder bumps & attach	< 5	< 50,000	< 530
Palladium	C1m	Surface mount capacitors / resistors	< 0.100	< 1,000	< 11
Silver	C1n	Surface mount resistors	< 0.0025	< 25	< 0.27

1. This reference corresponds to the item number of each material of interest as defined in Section C of EIA's Material Declaration Guide (February 2002). See "EIA Materials of Interest" on page 4-10 for a complete listing.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

The following materials are not listed in EIA's Material Declaration Template, but are contained in this package.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

Material of Interest	Wt%	ppm	Mg
Acrylic	< 0.035	< 350	< 3.7
AL2O3 Ceramic	< 0.200	< 2,000	< 21
Barium Titanate	< 1.5	< 15,000	< 159
Bismuth	< 0.0075	< 75	< 0.80
BT Resin	< 15	< 150,000	< 1590
Epoxy	< 5	< 50,000	< 530
Glass	< 0.0025	< 25	< 0.27
Iron	< 0.800	< 8,000	< 85
Lead-Borate Glass	< 0.010	< 100	< 1.1
Phosphorus	< 0.025	< 250	< 2.7
Polyester	< 0.100	< 1,000	< 11
Ruthenium Oxide	< 0.0075	< 75	< 0.80
Silicon	< 2	< 20,000	< 212
Silicone elastomer	< 1.0	< 10,000	< 106
SiO2 Filler (Fused Silica)	< 1.2	< 12,000	< 127
SiO2 Glass Mesh	< 19	< 190,000	< 2014
Tin	< 0.700	< 7,000	< 74
Zinc	< 0.050	< 500	< 5.3

MATERIAL DECLARATION DATA SHEET

Package: Barton, 27493 Average Weight: 11.0 grams
 Description: Athlon, OPGA, Green Contact: jacquana.diep@amd.com

CONTROLLED MATERIALS

The product neither contains nor was manufactured with materials listed in Section A of EIA's Material Declaration Template.

RESTRICTED MATERIALS

The product does not contain listed materials in prohibited applications indicated in Section B of EIA's Material Declaration Template.

MATERIALS OF INTEREST

The product does contain listed materials of interest as indicated by Section C of EIA's Material Declaration Template. These materials are listed in the following table.

Material of Interest	Reference	Description of Use	Wt%	ppm	mg
Antimony	C1a	Pin attachments	< 0.250	< 2,500	< 29
Copper	C1k	Pins and Internal circuitry	< 55	< 550,000	< 6050
Gold	C1l	Internal circuitry & contact plating	< 0.015	< 150	< 1.7
Nickel	C1h	Plating of pins	< 0.300	< 3,000	< 33
Pb (Lead)	C1f	Solder bumps & attach	< 5	< 50,000	< 550
Palladium	C1m	Surface mount capacitors / resistors	< 0.100	< 1,000	< 111
Silver	C1n	Surface mount resistors	< 0.0025	< 25	< 0.28

1. This reference corresponds to the item number of each material of interest as defined in Section C of EIA's Material Declaration Guide (February 2002). See "EIA Materials of Interest" on page 4-10 for a complete listing.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

The following materials are not listed in EIA's Material Declaration Template, but are contained in this package.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

Material of Interest	Wt%	ppm	mg
Acrylic	< 0.030	< 300	< 3.3
AL2O3 Ceramic	< 0.200	< 2,000	< 22
Barium Titanate	< 1.5	< 15,000	< 165
Bismuth	< 0.0075	< 75	< 0.83
BT Resin	< 14.5	< 145,000	< 1595
Epoxy	< 3.0	< 30,000	< 330
Glass	< 0.0025	< 25	< 0.28
Iron	< 0.800	< 8,000	< 88
Lead-Borate Glass	< 0.010	< 100	< 1.1
Phosphorus	< 0.0250	< 250	< 2.8
Polyester	< 0.100	< 1,000	< 11
Ruthenium Oxide	< 0.0075	< 75	< 0.83
Silicon	< 2.0	< 20,000	< 220
Silicone elastomer	< 1.0	< 10,000	< 110
SiO2 Filler (Fused Silica)	< 0.900	< 9,000	< 99
SiO2 Glass Mesh	< 18	< 180,000	< 1980
Tin	< 0.700	< 7,000	< 77
Zinc	< 0.050	< 500	< 5.5

MATERIAL DECLARATION DATA SHEET

Package: Sledge Hammer 27872 Average Weight: 39.9 grams
 Description: Athlon 64, uOPGA, 754 pins Contact: jacquana.diep@amd.com

CONTROLLED MATERIALS

The product neither contains nor was manufactured with materials listed in Section A of EIA's Material Declaration Template.

RESTRICTED MATERIALS

The product does not contain listed materials in prohibited applications indicated in Section B of EIA's Material Declaration Template.

MATERIALS OF INTEREST

The product does contain listed materials of interest as indicated by Section C of EIA's Material Declaration Template. These materials are listed in the following table.

Material of Interest	Reference ¹	Description of Use	wt%	ppm	mg
Antimony	C1a	Pin attachments	< 0.050	< 500	< 20
Copper	C1k	Pins and Internal circuitry	< 11	< 110,000	< 4,384
Copper (Lid)	C1k	Lid	< 80	< 800,000	< 31,887
Gold	C1l	Internal circuitry & contact plating	< 0.016	< 160	< 6.4
Nickel	C1h	Plating of pins, surface capacitors	< 0.071	< 710	< 28
Nickel (Lid)	C1h	Lid	< 0.66	< 6,600	< 263
Palladium	C1m	Surface mount capacitors / resistors	< 0.015	< 150	< 6.0
Pb (Lead)	C1f	Solder bumps & attach	< 1.1	< 11,000	< 438

1. This reference corresponds to the item number of each material of interest as defined in Section C of EIA's Material Declaration Guide (February 2002). See "EIA Materials of Interest" on page 4-10 for a complete listing.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

The following materials are not listed in EIA's Material Declaration Template, but are contained in this package.

Material	Wt%	ppm	mg
Aluminum	< 0.39	< 3,900	< 155
Barium Titanate	< 0.27	< 2,700	< 108
BT Resin	< 2.6	< 26,000	< 1,036
Epoxy	< 0.87	< 8,700	< 347
Iron	< 0.087	< 870	< 35
Phosphorus	< 0.0019	< 19	< 0.76
Silicon	< 0.85	< 8,500	< 339
Silicone elastomer	< 0.34	< 3,400	< 136
SiO2 Filler	< 0.30	< 3,000	< 120
SiO2 glass mesh	< 3.2	< 32,000	< 1,275
Tin	< 0.14	< 1,400	< 56
Zinc	< 0.0038	< 38	< 1.5
Zinc oxide	< 0.14	< 1,400	< 56

MATERIAL DECLARATION DATA SHEET

Package: Barton 27492

Average Weight: 4.4 grams

Description: Athlon, uOPGA, Brown

Contact: jacquana.diep@amd.com

CONTROLLED MATERIALS

- The product neither contains nor was manufactured with materials listed in Section A of EIA's Material Declaration Template.

RESTRICTED MATERIALS

- The product does not contain listed materials in prohibited applications indicated in Section B of EIA's Material Declaration Template.

MATERIALS OF INTEREST

- The product does contain listed materials of interest as indicated by Section C of EIA's Material Declaration Template. These materials are listed in the following table.

Material of Interest	Reference ¹	Description of Use	wt%	ppm	mg
Antimony	C1a	Pin attachments	< 0.35	< 3,500	< 15
Copper	C1k	Pins and Internal circuitry	< 46	< 460,000	< 2,018
Gold	C1l	Internal circuitry & contact plating	< 0.023	< 230	< 1.0
Nickel	C1h	Plating of pins, surface capacitors	< 0.70	< 7,000	< 31
Palladium	C1m	Surface mount capacitors / resistors	< 0.063	< 630	< 2.8
Pb (Lead)	C1f	Solder bumps & attach	< 6.4	< 64,000	< 281
Silver	C1n	Resistors	< 0.0027	< 27	< 0.12

1. This reference corresponds to the item number of each material of interest as defined in Section C of EIA's Material Declaration Guide (February 2002). See "EIA Materials of Interest" on page 4-10 for a complete listing.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

The following materials are not listed in EIA's Material Declaration Template, but are contained in this package.

Material	Wt%	ppm	mg
AL2O3 Ceramic	< 0.19	< 1,900	< 8.3
Barium Titanate	< 1.3	< 13,000	< 57
Bismuth	< 0.015	< 150	< 0.66
BT Resin	< 16	< 160,000	< 702
Epoxy	< 5.5	< 55,000	< 241
Glass	< 0.00063	< 6.3	< 0.028
Iron	< 0.51	< 5,100	< 22
Lead-Borate Glass	< 0.0075	< 75	< 0.33
Phosphorus	< 0.011	< 110	< 0.48
Ruthenium Oxide	< 0.0042	< 42	< 0.18
Silicon	< 4.1	< 41,000	< 180
SiO2 Filler	< 1.4	< 14,000	< 61
SiO2 glass mesh	< 20	< 200,000	< 877
Tin	< 0.7	< 7,000	< 31
Zinc	< 0.022	< 220	< 0.96



MATERIAL DECLARATION DATA SHEET

Package: Barton 27745

Average Weight: 4.4 grams

Description: Athlon, uOPGA, Brown

Contact: jacquana.diep@amd.com

CONTROLLED MATERIALS

- The product neither contains nor was manufactured with materials listed in Section A of EIA's Material Declaration Template.

RESTRICTED MATERIALS

- The product does not contain listed materials in prohibited applications indicated in Section B of EIA's Material Declaration Template.

MATERIALS OF INTEREST

- The product does contain listed materials of interest as indicated by Section C of EIA's Material Declaration Template. These materials are listed in the following table.

Material of Interest	Reference ¹	Description of Use	wt%	ppm	mg
Antimony	C1a	Pin attachments	< 0.34	< 3,400	< 15
Copper	C1k	Pins and Internal circuitry	< 46	< 460,000	< 2,018
Gold	C1l	Internal circuitry & contact plating	< 0.023	< 230	< 1.0
Nickel	C1h	Plating of pins, surface capacitors	< 0.7	< 7,000	< 31
Palladium	C1m	Surface mount capacitors / resistors	< 0.063	< 630	< 2.8
Pb (Lead)	C1f	Solder bumps & attach	< 6.4	< 64,000	< 281
Silver	C1n	Resistors	< 0.0027	< 27	< 0.12

1. This reference corresponds to the item number of each material of interest as defined in Section C of EIA's Material Declaration Guide (February 2002). See "EIA Materials of Interest" on page 4-10 for a complete listing.

ADDITIONAL INFORMATION / ADDITIONAL MATERIALS

The following materials are not listed in EIA's Material Declaration Template, but are contained in this package.

Material	Wt%	ppm	mg
AL2O3 Ceramic	< 0.19	< 1,900	< 8.3
Barium Titanate	< 1.3	< 13,000	< 57
BT Resin	< 16	< 160,000	< 702
Epoxy	< 5.5	< 55,000	< 241
Glass	< 0.00063	< 6.3	< 0.028
Iron	< 0.51	< 5,100	< 22
Lead-Borate Glass	< 0.0074	< 74	< 0.32
Phosphorus	< 0.011	< 110	< 0.48
Ruthenium Oxide	< 0.0042	< 42	< 0.18
Silicon	< 4.1	< 41,000	< 180
SiO2 Filler	< 1.4	< 14,000	< 61
SiO2 glass mesh	< 20	< 200,000	< 877
Tin	< 0.76	< 7,600	< 33
Zinc	< 0.022	< 220	< 0.96